



## SUNLU Filaments Parameters

Material	Printing Temp. (°C)	Platform Temp. (°C)	Bedding plate (°C)	Thermal Deformation Temp. (°C)	Melt Mass Flow Rate	Density (g/cm³)	Tensile Strength (MPa)	Resilience Elongation (%)	Water Absorption (%)	Tolerance
PLA	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-150	55	7-9g/10min (100°C, 2.18kg)	1.24	11-12	4	0.50%	±0.02mm
PLA+	210-235	70-100°C	100-150	57	9-11g/10min (90°C, 2.18kg)	1.24	11-12	15	0.50%	±0.02mm
PLA Red wood	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-150	55	7-9g/10min (100°C, 2.18kg)	1.24	11-12	4	0.50%	±0.02mm
PA6	200-240	1. No need when with glue stick 2. 60-80°C without glue stick	140-145	54	11-13g/10min (100°C, 2.18kg)	1.14	8-9	110	0.10%	±0.02mm
PLA Carbon Fiber	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-150	55	7-9g/10min (100°C, 2.18kg)	1.24	11-12	4	0.70%	±0.02mm
ABS	240-260	Get metal cooling with Infrared insulation and semi sealed?	120-140	48	10-11g/10min (220°C, 1.98kg)	1.04	4-11	45	1.10%	±0.02mm
ABS High Temp.	250-270	Get metal cooling with Infrared insulation and semi sealed?	150-170	35	10-11g/10min (220°C, 1.98kg)	1.07	6-13	20	1.10%	±0.02mm
ABS Resistant	250-270	Get metal cooling with Infrared insulation and semi sealed?	170-190	27	10-11g/10min (220°C, 1.98kg)	1.03	6-11	19	1.10%	±0.02mm
HDPE	200-220	30-100°C	100-150	51	10-12g/10min (200°C, 1.94kg)	1.01	5-7	31	1.30%	±0.02mm
PC/PC	200-230	1. No need when with glue stick 2. 70-80°C without glue stick	150-160	55	6-11g/10min (200°C, 2.16kg)	1.20	6-8	210	0.30%	±0.02mm
WPC/CF	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-150	51	8-11g/10min (100°C, 2.16kg)	1.33	6-13	4	1.10%	±0.02mm
TPU	200-230	No need	100-150	4	11-13g/10min (100°C, 2.16kg)	1.21	7	600	0.70%	±0.02mm
PA	240-260	30-100°C	120-140	58	14-16g/10min (200°C, 2.16kg)	1.13	5-7	200	0.50%	±0.02mm
PE	200-230	Get metal cooling with Infrared insulation and semi sealed?	200-240	59	10-12g/10min (220°C, 2.12kg)	1.2	5-6	110	0.30%	±0.02mm
ASA	240-260	1. No need when with glue stick 2. 60-80°C without glue stick	140-145	4	14-16g/10min (200°C, 2.16kg)	1.24	5-11	30%	0.10%	±0.02mm
PC	200-230	No need	50-70	4	11-13g/10min (100°C, 2.16kg)	1.21	7	200	0.70%	±0.02mm
TPU40	200-240	30-100°C	150-170	52	9-11g/10min (220°C, 2.18kg)	1.19	6-12	12	0.50%	±0.02mm
ASA	250-280	30-100°C	170-190	28	9-12g/10min (220°C, 1.98kg)	1.24	6-10	24	1.30%	±0.02mm
PLA Carbon Fiber	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-150	52	11-13g/10min (220°C, 2.18kg)	1.2	11-11	3	0.50%	±0.02mm